

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
LE ZHANG	11/16/2022
QING FENG	11/16/2022
SIQI WANG	11/16/2022
CHU SHEN	11/16/2022
XIULING HE	11/16/2022
BO YANG	11/16/2022
DONG MIAO	11/16/2022
RECEIVING PARTY DATA	
Name:	XI'AN TAIJIN INDUSTRIAL ELECTROCHEMICAL TECHNOLOGY CO., LTD.
Street Address:	NO. 15, XIJIN ROAD, JINGWEI INDUSTRIAL PARK
Internal Address:	XI'AN ECONOMIC AND TECHNOLOGICAL DEV. ZONE
City:	XI'AN CITY, SHAANXI PROVINCE
State/Country:	CHINA
Postal Code:	710299
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	18063864
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NAME OF SUBMITTER:	MEI LIN WONG
SIGNATURE:	/Mei Lin Wong/

DATE SIGNED:	12/09/2022
Total Attachments: 2 source=a704-Assignment-20221116#page1.tif source=a704-Assignment-20221116#page2.tif	

ASSIGNMENT

WHEREAS #1: Le ZHANG; #2: Qing FENG; #3: Siqi WANG; #4: Chu SHEN; #5: Xiuling HE; #6: Bo YANG; and #7: Dong MIAO, the assignor(s), whose mailing address is #1-#7: No. 15, Xijin Road, JingWei Industrial Park, Xi'an Economic and Technological Development Zone, Xi'an City, Shaanxi Province, P.R. China, P.C:710299,

have invented certain new and useful improvements in an invention relating to and entitled, Large-width Cathode Roller for Producing High-strength Ultra-thin Copper Foil, the invention, as fully set forth and described in an application for Letters Patent to be filed at the United States Patent and Trademark Office and naming the assignors as inventors and applicants;

AND WHEREAS: Xi'an Taijin Industrial Electrochemical Technology Co., Ltd. of China, the assignee, whose mailing address is: No. 15, Xijin Road, JingWei Industrial Park, Xi'an Economic and Technological Development Zone, Xi'an City, Shaanxi Province, P.R. China, P.C:710299,

is desirous of acquiring the entire right, title and interest in and to said invention, and in and to Any Letters Patent that may be obtained therefor;

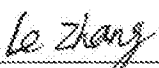
NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, receipt of which is hereby acknowledged, the assignors, do hereby confirm that they have sold, assigned and transferred, and do hereby sell, assign and transfer to the assignee the full and exclusive right to the said invention in the United States and their entire right, title and interest for the United States in and to the invention, together with their entire right, title and interest in and to said application, any and all divisional applications thereof, and any and all Letters Patent of the United States which may issue or be reissued for the invention;

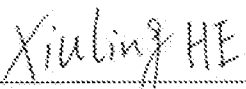
AND the assignors hereby authorize and request the Director of the United States Patent and Trademark Office to issue to said assignee of any and all said Letters Patent not already issued as the assignee of their entire right, title and interest in and to the same, for the sole use and benefit of said assignee, its successors, assigns or legal representatives, to the full end of the term for which said Patent may be granted, as fully and entirely as the same would have been held by the assignors had this assignment and sale not been made.

AND the assignors, on behalf of themselves and their executors and administrators, hereby covenant and agree to do all such lawful acts and things and to execute without further consideration such further lawful assignments, documents, assurances, applications, and other instruments as may reasonably be required by said assignee, its successors, assigns or legal representatives, to obtain any and all Letters Patent of the United States for said invention and vest the same in said assignee, its successors, assigns or legal representatives.

SIGNED on this [16] day of [November], 2022

SIGNED on this [16] day of [November], 2022


[Signature#1]
Le ZHANG


[Signature#5]
Xiuling HE

SIGNED on this [16] day of [November], 2022

SIGNED on this [16] day of [November], 2022

Qing Feng [Signature#2]
Qing FENG

Bo Yang [Signature#6]
Bo YANG

SIGNED on this [16] day of [November], 2022

SIGNED on this [16] day of [November], 2022

Siqi Wang [Signature#3]
Siqi WANG

Dong Miao [Signature#7]
Dong MIAO

SIGNED on this [16] day of [November], 2022

Chu Shen [Signature#4]
Chu SHEN